

2.5/3D Packaging NEPP ETW

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Overview - Review today's agenda

- Discussion of NEPP 2.5/3D – Sheldon
- Provide background, technology roadmaps,
- overview of NEPP products/deliverables
- “Statistics and Physics in Reliability” – Lloyd
- A rigorous and foundational understanding of physics and statistics is needed to address the reliability problems of 2.5/3D packaging technology.
- NEPP Packaging Tasks – (Popelar, Suh, Ghaffarian)
- Updates on current results
- DTRA 3D Packaging – Alles
- Radiation effects in complex structures with >50% High Z materials
- 2.5/3D Roadmaps and OSAT Advanced Packaging
- Commercial growth and development of these technologies is continual and expansive. Need SOA industry partners to provide guidance and direction on options for NASA.